

12
Cover 14.

9. A semiconductor device package according to claim 5, wherein the semiconductor device is attached to the first portion of the leadframe by solder.

10. A semiconductor device package according to claim 5, wherein the semiconductor device is a surface mount semiconductor device.

11. A semiconductor device package according to claim 5, wherein the semiconductor device is a power semiconductor device.

12. A semiconductor device package according to claim 5, wherein the first portion of the leadframe forms a heat sink for the semiconductor device and a surface of the first portion is not covered by the electrically insulating material.
